

**N-Ch 40V Fast Switching MOSFETs**

- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

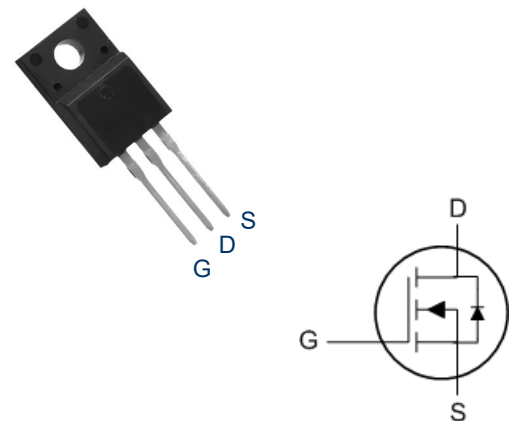
**Product Summary**


| BVDSS | RDSON | ID   |
|-------|-------|------|
| 40V   | 2.5mΩ | 150A |

**Description**

The UD150N04FT is the high performance complementary N-ch MOSFETs with high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The UD150N04FT meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

**TO220F Pin Configuration**

**Absolute Maximum Ratings**

| Symbol                      | Parameter                                      | Rating     | Units            |
|-----------------------------|------------------------------------------------|------------|------------------|
| $V_{DS}$                    | Drain-Source Voltage                           | 40         | V                |
| $V_{GS}$                    | Gate-Source Voltage                            | $\pm 20$   | V                |
| $I_D@T_C=25^\circ\text{C}$  | Continuous Drain Current, $V_{GS} @ 10V^{1,6}$ | 150        | A                |
| $I_D@T_C=100^\circ\text{C}$ | Continuous Drain Current, $V_{GS} @ 10V^{1,6}$ | 85         | A                |
| $I_{DM}$                    | Pulsed Drain Current <sup>2</sup>              | 560        | A                |
| EAS                         | Single Pulse Avalanche Energy <sup>3</sup>     | 726        | mJ               |
| $I_{AS}$                    | Avalanche Current                              | ---        | A                |
| $P_D@T_C=25^\circ\text{C}$  | Total Power Dissipation <sup>4</sup>           | 115        | W                |
| $T_{STG}$                   | Storage Temperature Range                      | -55 to 150 | $^\circ\text{C}$ |
| $T_J$                       | Operating Junction Temperature Range           | -55 to 150 | $^\circ\text{C}$ |

**Thermal Data**

| Symbol          | Parameter                                        | Typ. | Max. | Unit               |
|-----------------|--------------------------------------------------|------|------|--------------------|
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient <sup>1</sup> | ---  | ---  | $^\circ\text{C/W}$ |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case <sup>1</sup>    | ---  | 1.3  | $^\circ\text{C/W}$ |

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

| Symbol                         | Parameter                                      | Conditions                                                 | Min. | Typ. | Max.      | Unit                |
|--------------------------------|------------------------------------------------|------------------------------------------------------------|------|------|-----------|---------------------|
| $BV_{DSS}$                     | Drain-Source Breakdown Voltage                 | $V_{GS}=0V$ , $I_D=250\mu A$                               | 40   | ---  | ---       | V                   |
| $\Delta BV_{DSS} / \Delta T_J$ | $BV_{DSS}$ Temperature Coefficient             | Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$         | ---  | ---  | ---       | $V/^\circ\text{C}$  |
| $R_{DS(ON)}$                   | Static Drain-Source On-Resistance <sup>2</sup> | $V_{GS}=10V$ , $I_D=20A$                                   | ---  | 2.5  | 3.1       | $m\Omega$           |
|                                |                                                | $V_{GS}=4.5V$ , $I_D=20A$                                  | ---  | 3.5  | 4.7       |                     |
| $V_{GS(th)}$                   | Gate Threshold Voltage                         | $V_{GS}=V_{DS}$ , $I_D=250\mu A$                           | 1.0  | 1.7  | 2.5       | V                   |
| $\Delta V_{GS(th)}$            | $V_{GS(th)}$ Temperature Coefficient           |                                                            | ---  | ---  | ---       | $mV/^\circ\text{C}$ |
| $I_{DSS}$                      | Drain-Source Leakage Current                   | $V_{DS}=40V$ , $V_{GS}=0V$ , $T_J=25^\circ\text{C}$        | ---  | ---  | 1         | $\mu A$             |
|                                |                                                | $V_{DS}=40V$ , $V_{GS}=0V$ , $T_J=100^\circ\text{C}$       | ---  | ---  | 100       |                     |
| $I_{GSS}$                      | Gate-Source Leakage Current                    | $V_{GS}=\pm 20V$ , $V_{DS}=0V$                             | ---  | ---  | $\pm 100$ | nA                  |
| $g_{fs}$                       | Forward Transconductance                       | $V_{DS}=5V$ , $I_D=20A$                                    | ---  | 38   | ---       | S                   |
| $R_g$                          | Gate Resistance                                | $V_{DS}=0V$ , $V_{GS}=0V$ , $f=1\text{MHz}$                | ---  | 0.67 | ---       | $\Omega$            |
| $Q_g$                          | Total Gate Charge                              | $V_{DS}=20V$ , $V_{GS}=10V$ , $I_D=20A$                    | ---  | 112  | ---       | nC                  |
| $Q_{gs}$                       | Gate-Source Charge                             |                                                            | ---  | 16.7 | ---       |                     |
| $Q_{gd}$                       | Gate-Drain Charge                              |                                                            | ---  | 26.5 | ---       |                     |
| $T_{d(on)}$                    | Turn-On Delay Time                             | $V_{GS}=10V$ , $V_{DD}=20V$ ,<br>$R_G=3\Omega$ , $I_D=10A$ | ---  | 18   | ---       | ns                  |
| $T_r$                          | Rise Time                                      |                                                            | ---  | 4.4  | ---       |                     |
| $T_{d(off)}$                   | Turn-Off Delay Time                            |                                                            | ---  | 67   | ---       |                     |
| $T_f$                          | Fall Time                                      |                                                            | ---  | 9.5  | ---       |                     |
| $C_{iss}$                      | Input Capacitance                              | $V_{DS}=20V$ , $V_{GS}=0V$ , $f=1\text{MHz}$               | ---  | 6460 | ---       | pF                  |
| $C_{oss}$                      | Output Capacitance                             |                                                            | ---  | 455  | ---       |                     |
| $C_{rss}$                      | Reverse Transfer Capacitance                   |                                                            | ---  | 276  | ---       |                     |

**Diode Characteristics**

| Symbol   | Parameter                                | Conditions                                      | Min. | Typ. | Max. | Unit |
|----------|------------------------------------------|-------------------------------------------------|------|------|------|------|
| $I_S$    | Continuous Source Current <sup>1,5</sup> | $V_G=V_D=0V$ , Force Current                    | ---  | ---  | 150  | A    |
| $V_{SD}$ | Diode Forward Voltage <sup>2</sup>       | $V_{GS}=0V$ , $I_S=1A$ , $T_J=25^\circ\text{C}$ | ---  | ---  | 1.2  | V    |

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $T_J=25^\circ\text{C}$ ,  $V_{DD}=40V$ ,  $V_G=10V$ ,  $R_g=25\Omega$ ,  $L=0.5\text{mH}$ .
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

## Typical Electrical And Thermal Characteristics (Curves)

Figure 1. Output Characteristics

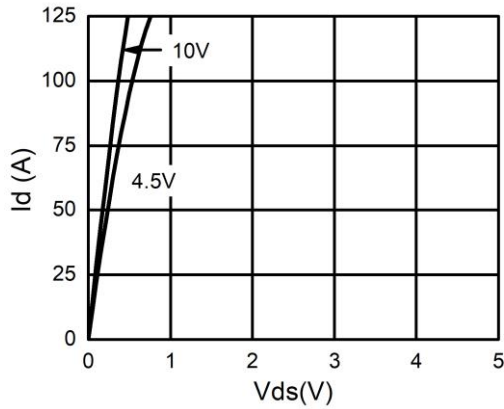


Figure 2. Transfer Characteristics

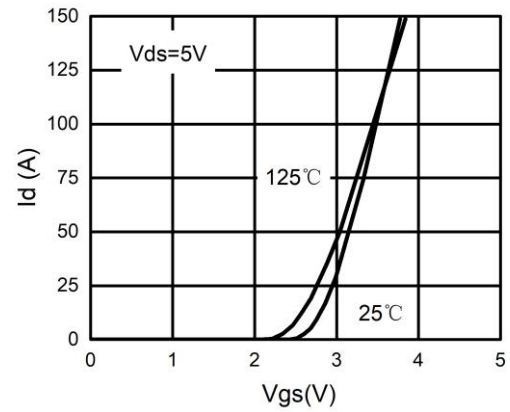


Figure 3. Power Dissipation

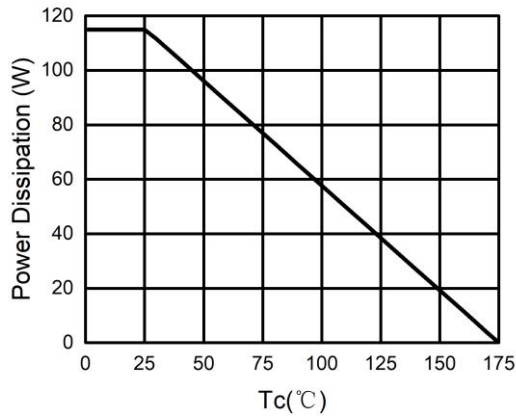


Figure 4. Drain Current

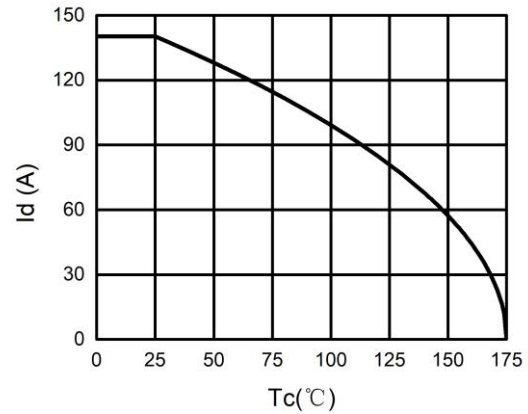


Figure 5.  $BV_{DSS}$  vs Junction Temperature

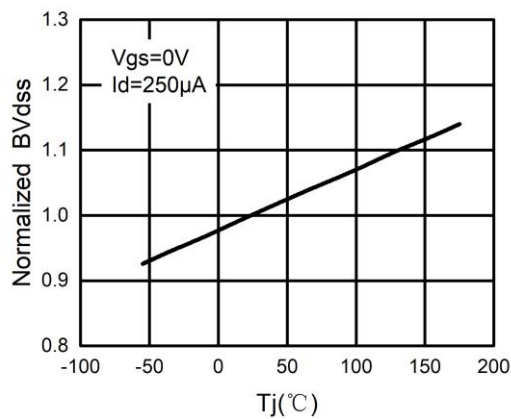
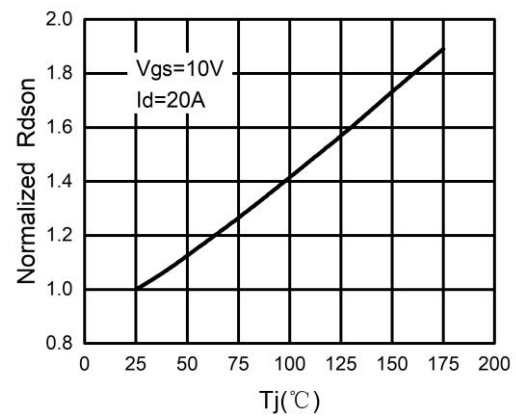
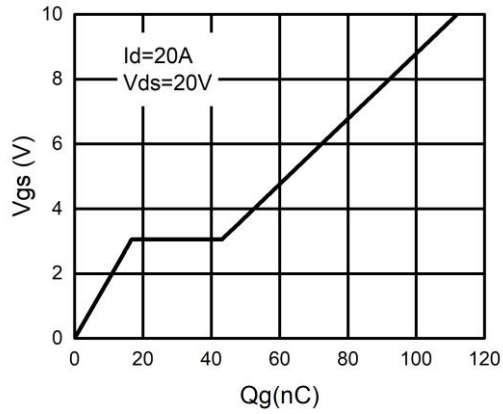


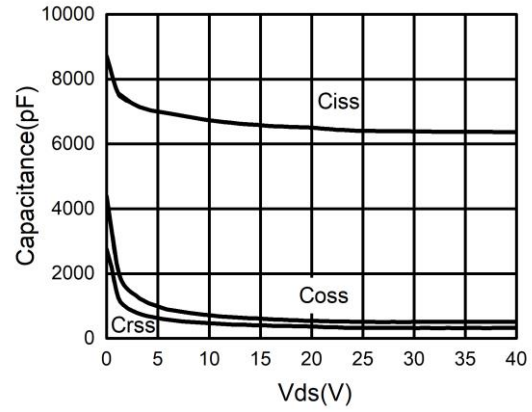
Figure 6.  $R_{DS(ON)}$  vs Junction Temperature



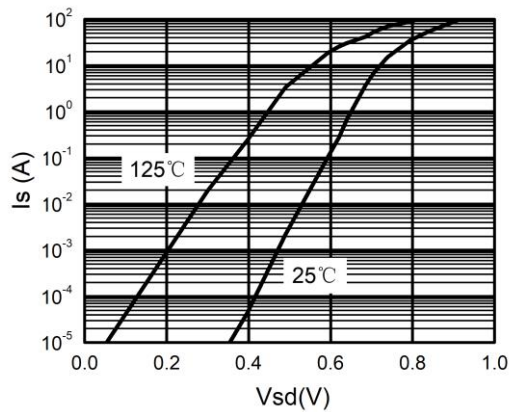
**Figure 7. Gate Charge Waveforms**



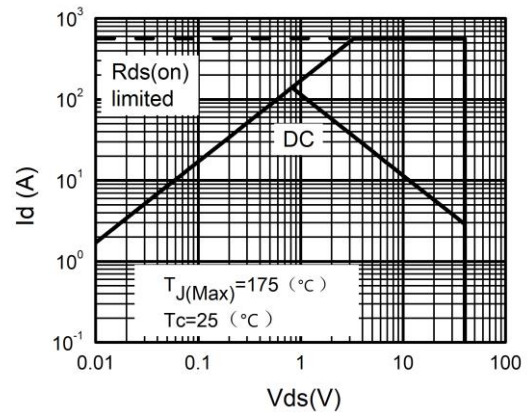
**Figure 8. Capacitance**



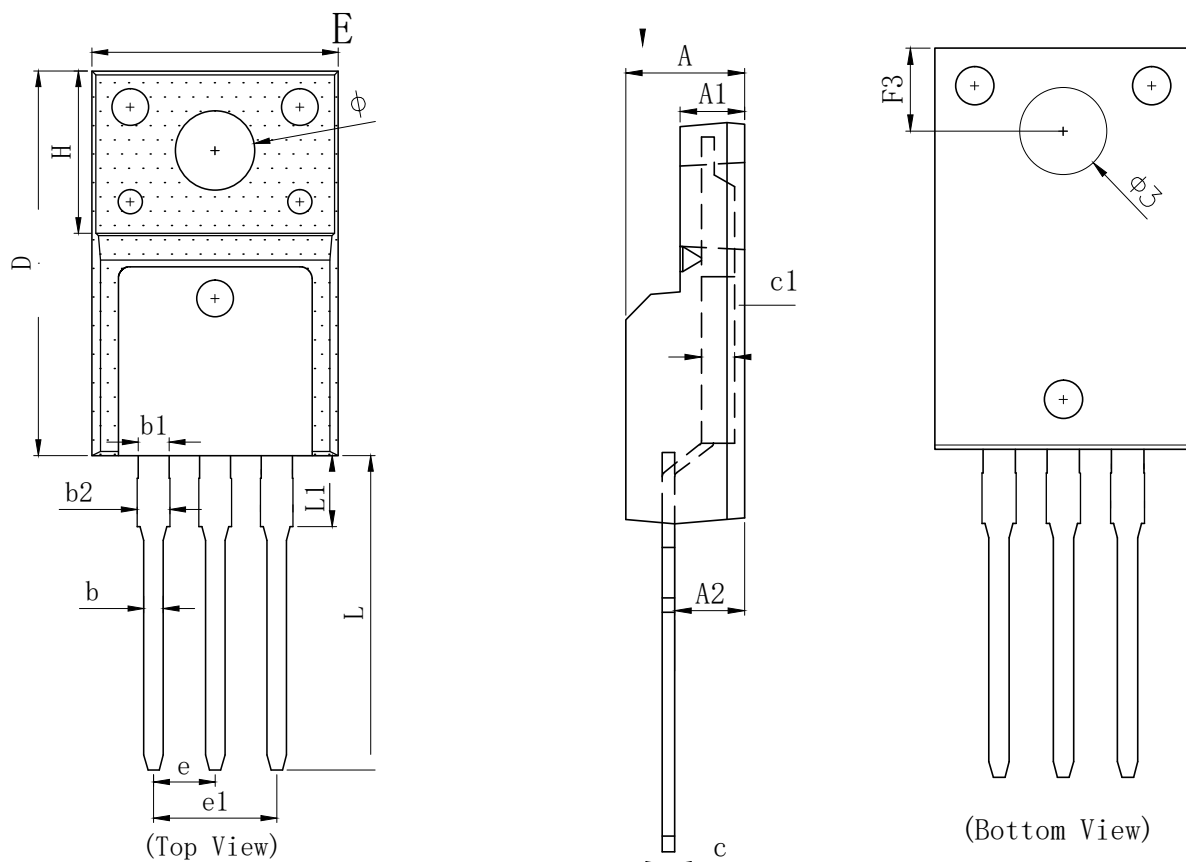
**Figure 9. Body-Diode Characteristics**



**Figure 10. Maximum Safe Operating Area**



### Mechanical Dimensions for TO-220F



| SYMBOL | MILLIMETER |        |        |
|--------|------------|--------|--------|
|        | MIN        | Typ.   | MAX    |
| A      | 4.500      | 4.700  | 4.900  |
| A1     | 2.340      | 2.540  | 2.740  |
| A2     | 2.560      | 2.760  | 2.960  |
| b      | 0.700      | 0.800  | 0.950  |
| b1     | 1.180      | 1.280  | 1.430  |
| b2     | 1.250      | 1.350  | 1.550  |
| c      | 0.400      | 0.500  | 0.650  |
| c1     | 1.200      | 1.300  | 1.350  |
| D      | 15.570     | 15.870 | 16.170 |
| H      | 6.700 REF  |        |        |
| E      | 9.960      | 10.160 | 10.360 |
| e      | 2.540 BSC  |        |        |
| e1     | 5.080 BSC  |        |        |
| L      | 12.680     | 12.980 | 13.280 |
| L1     | 2.780      | 2.930  | 3.080  |
| F3     | 3.150      | 3.300  | 3.450  |
| Φ      | 3.030      | 3.180  | 3.450  |
| Φ3     | 3.150      | 3.450  | 3.650  |